

**Amendments to the Claims**

This listing of claims will replace all prior versions, and listing, of claims in the application:

1. (previously presented) A method for bonding an integrated circuit device to a glass substrate comprising:  
placing a protecting circuit, connecting with an external circuit, on the glass substrate;  
providing a melting device with a first laser device and a second laser device;  
melting a predetermined portion of the protecting circuit by the first laser device, and melting a predetermined portion of the glass substrate by the second laser device; and  
bonding the integrated circuit device on the glass substrate.

2-3. (cancelled)

4. (Original) The method as claimed in claim 1, wherein the integrated circuit device comprises a driver circuit, a connecting wire, and a main substrate, and the connecting wire is in contact with the predetermined portion, melted by the melting device, of the glass substrate when the integrated circuit device is bonded to the glass substrate.

5. (Original) The method as claimed in claim 4, wherein the connecting wire is bonded to the protecting circuit of the glass substrate via an adhesive and a plurality of conductive particles.

6. (Original) The method as claimed in claim 1, wherein the predetermined portion of the glass substrate is located at edges of the glass substrate.

7-11. (cancelled)